Electronic Patent Application Fee Transmittal							
Application Number:	10679787						
Filing Date:	06-Oct-2003						
Title of Invention:	Connection site coating method and solder joints						
First Named Inventor:	Kejun Zeng						
Filer:	Yingsheng Tung/Jackie McBride						
Attorney Docket Number:	TI-36531						
Filed as Large Entity							
Utility Filing Fees							
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:							
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
Patent-Appeals-and-Interference:							
Filing a brief in support of an appeal		1402	1	500	500		
Post-Allowance-and-Post-Issuance:							
Extension-of-Time:							

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
	Total in USD (\$)			500